

# High-Pressure Chemical Vapor Deposition: An enabling technology for the fabrication of embedded indium-rich multiple heterostructures



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**Nikolaus Dietz**  
**Department of Physics & Astronomy**  
**Georgia State University; Atlanta GA**

<http://www.phy-astr.gsu.edu/dietzrg/>

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HPCVD growth

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Optical & Struct. Characterization

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Theory / modeling

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GaN & Structural Characterization

Prof. A. Hoffmann's research group at TUB:

Optical spectroscopy

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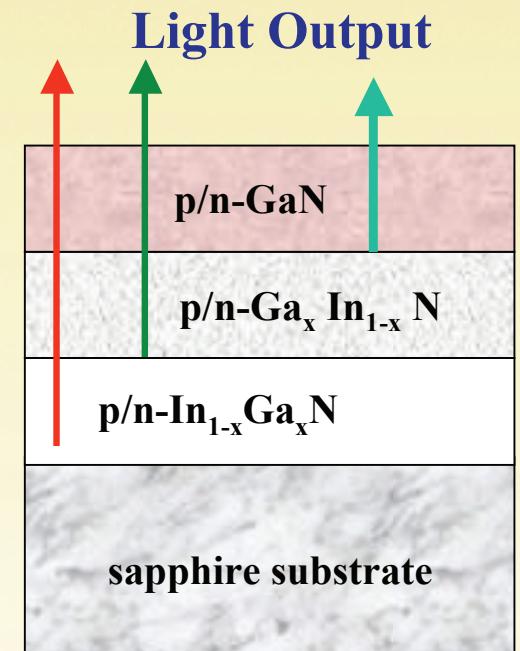
# Need for embedded InN and indium rich group III-nitride alloys and heterostructures

## ➤ High-efficient energy conversion systems

- ↳ Solid State Lightning (SSL)
- ↳ frequency agile lasers in wide spectral range
- ↳ monolithic integrated LED's / displays
- ↳ Monolithic integrated dual UV/IR detectors

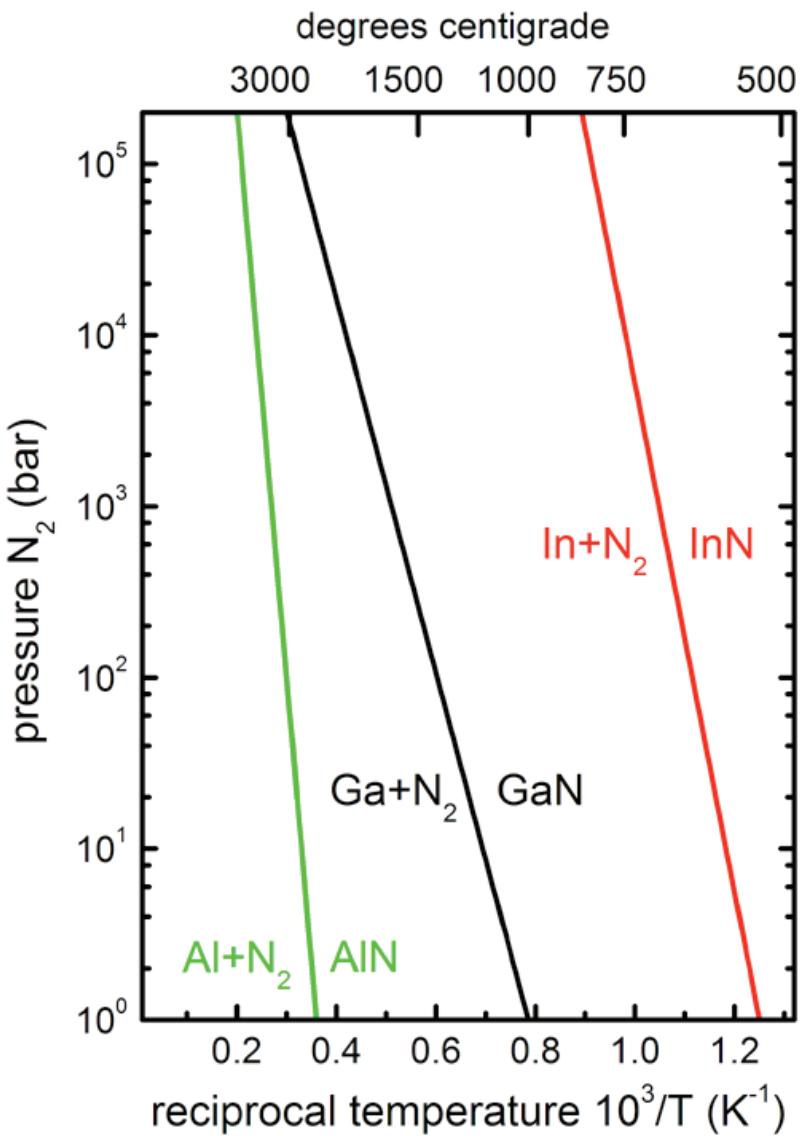


- High Speed Electronic Switching
- Monolithic integrated optoelectronics
- High Power Amplification
- High temperature device operation
- Room-temp. ferromagnetic group III-nitrides
- Terahertz device structures (emitters and detectors)



*However, high quality InN and indium-rich alloys are difficult to fabricated at optimum processing conditions!*

# The need of high-pressure CVD for InN growth and the fabrication of embedded $\text{GaN}/\text{In}_{1-x}\text{Ga}_x\text{N}/\text{GaN}$ structures



Materials Research Bulletin 5, 783 (1970)

Stabilization of InN under blanket of high pressure molecular nitrogen will enable processing at higher temperatures T than attainable at atmospheric and sub-atmospheric pressure.

$$p = 100 \text{ atm}$$

$$T = 900 - 1100 \text{ K}$$

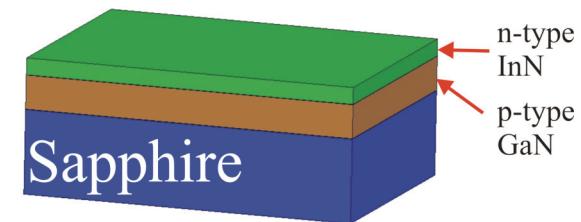
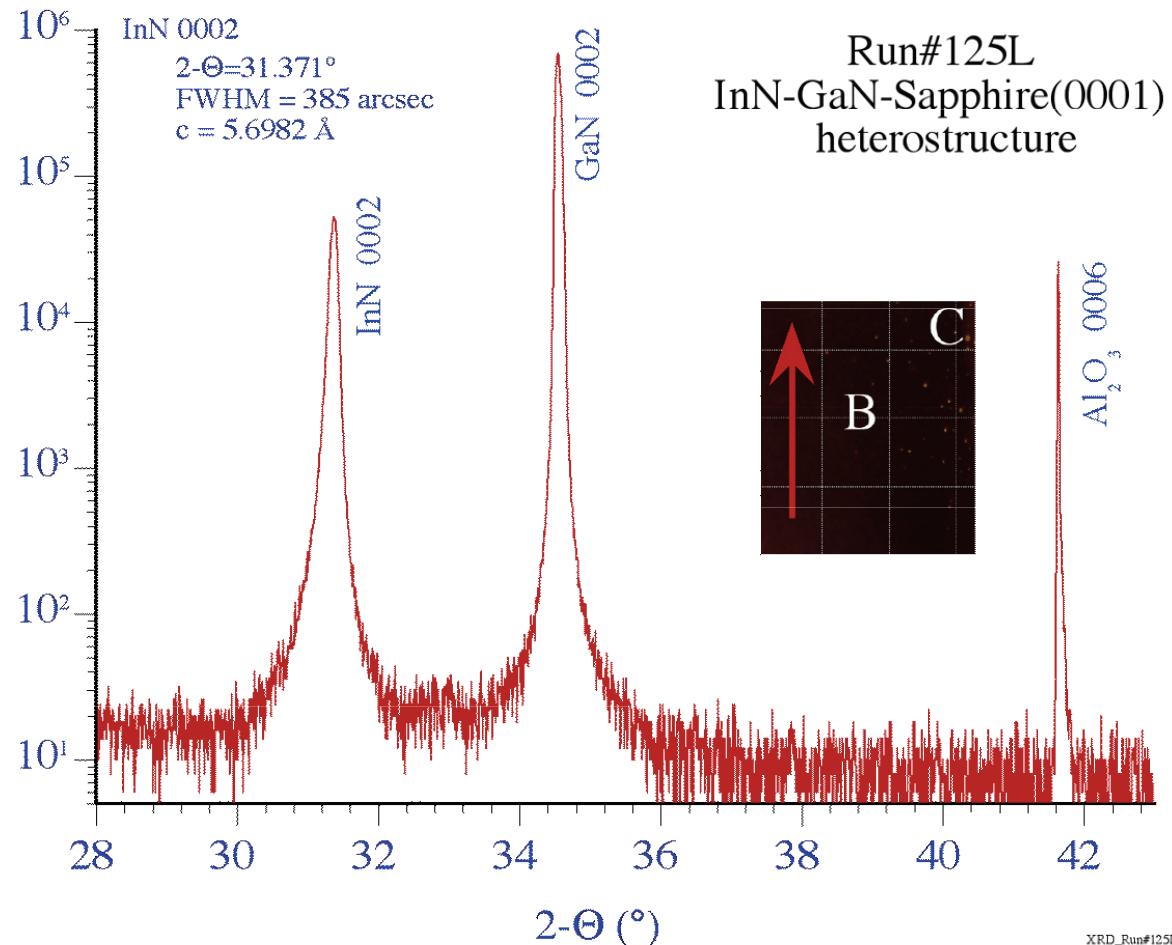
Potential gains of high T:

- *Improved nucleation kinetics*
- *Improved surface morphology*
- *Improved microstructure at growth temperature*
- ***Match of InN - GaN - AlN processing conditions***
- ***control of decomposition kinetics***

Drawback:

flow-kinetics can not be neglected!

# Does the HPCVD approach work? - Yes!



- Single crystal InN successfully deposited on GaN and sapphire epilayers
- FWHM of InN (0002) presently around 385 arc sec
- Carrier concentration in mid  $10^{19} \text{ cm}^{-3}$
- Mobility around  $600 \text{ cm}^2 \text{V}^{-1} \text{s}^{-1}$
- Absorption edge above 1.5 eV

Processing temperatures around 850 - 900 °C (@15 bar ) enables the fabrication of thick GaAlN/In<sub>1-x</sub>Ga<sub>x</sub>N/GaAlN multiple heterostructures.

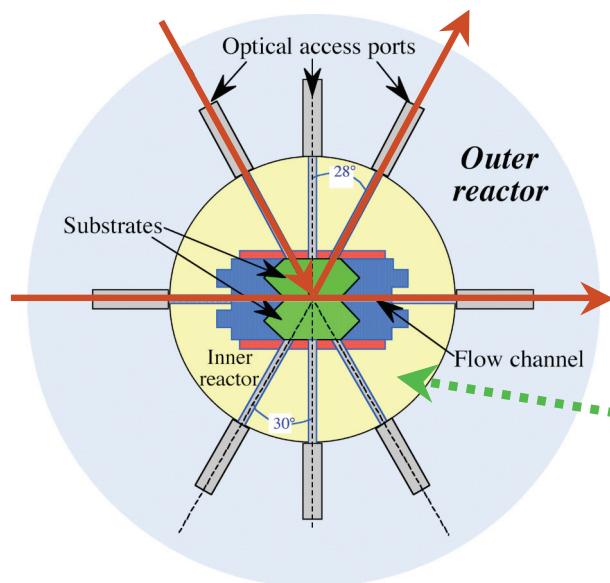


# High-Pressure Chemical Vapor Deposition “HPCVD”

## *Reactor Characteristics and Implementation\**

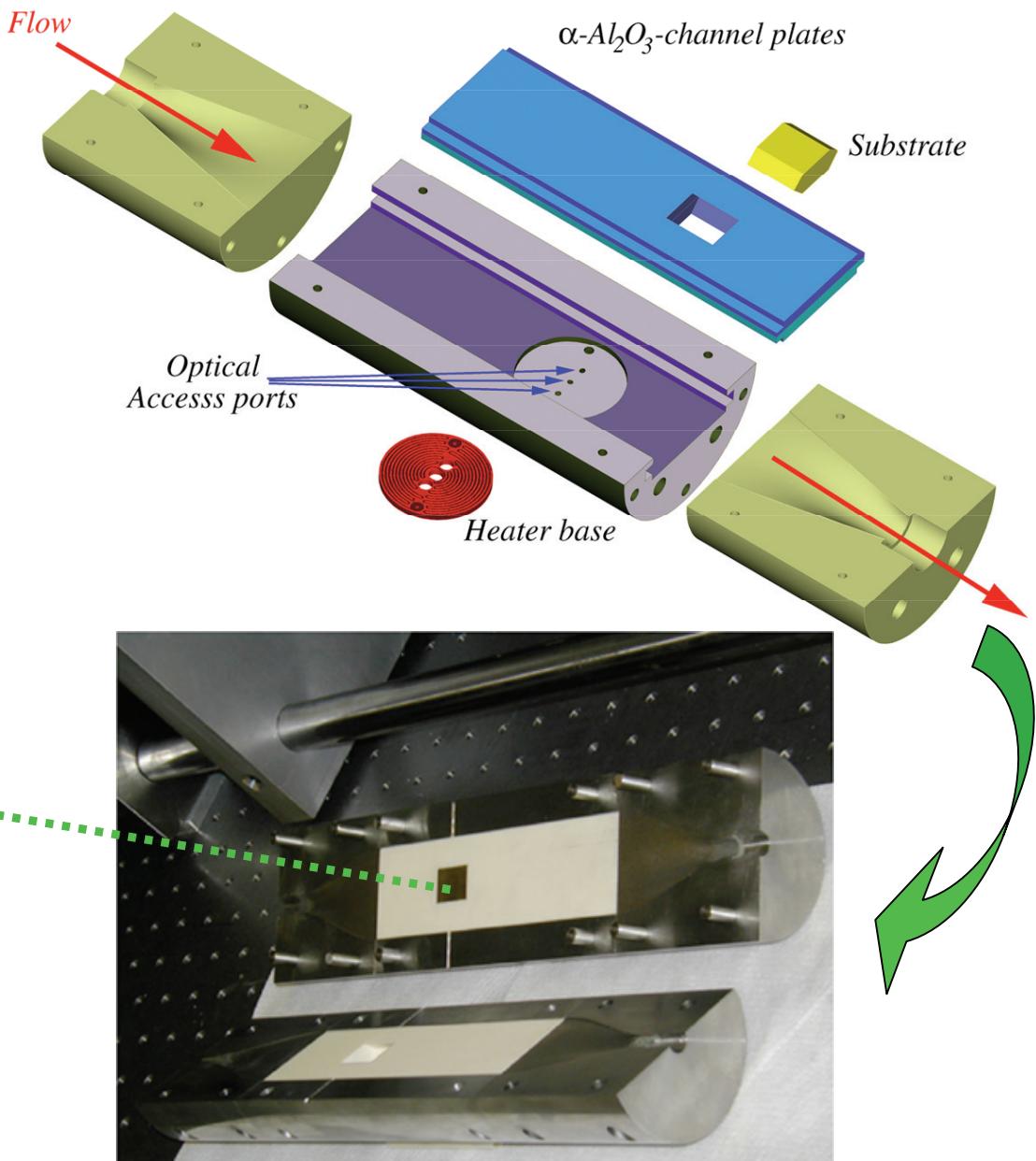
### ***Design Criteria***

- Maintenance of laminar gas flow (constant cross section)
- Symmetric substrates arrangements
- Access to Real Time monitoring



### ***Real-Time Monitoring***

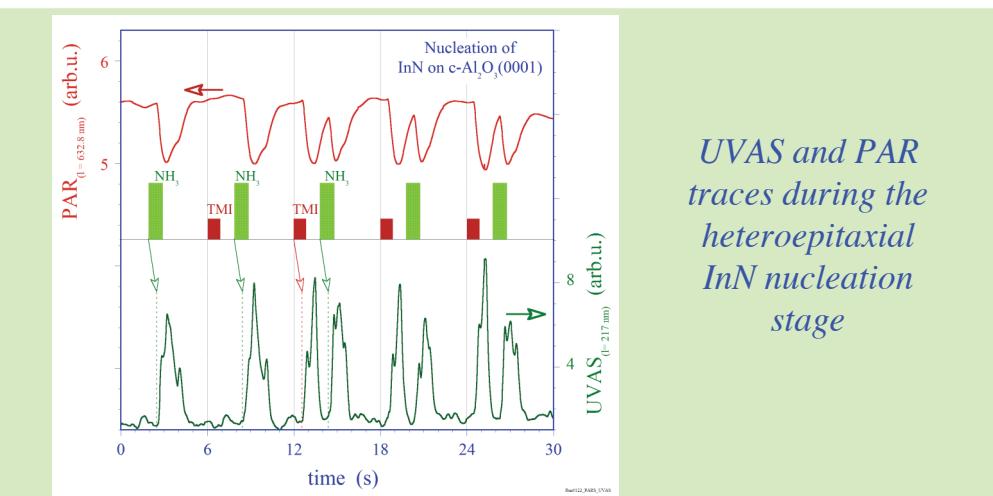
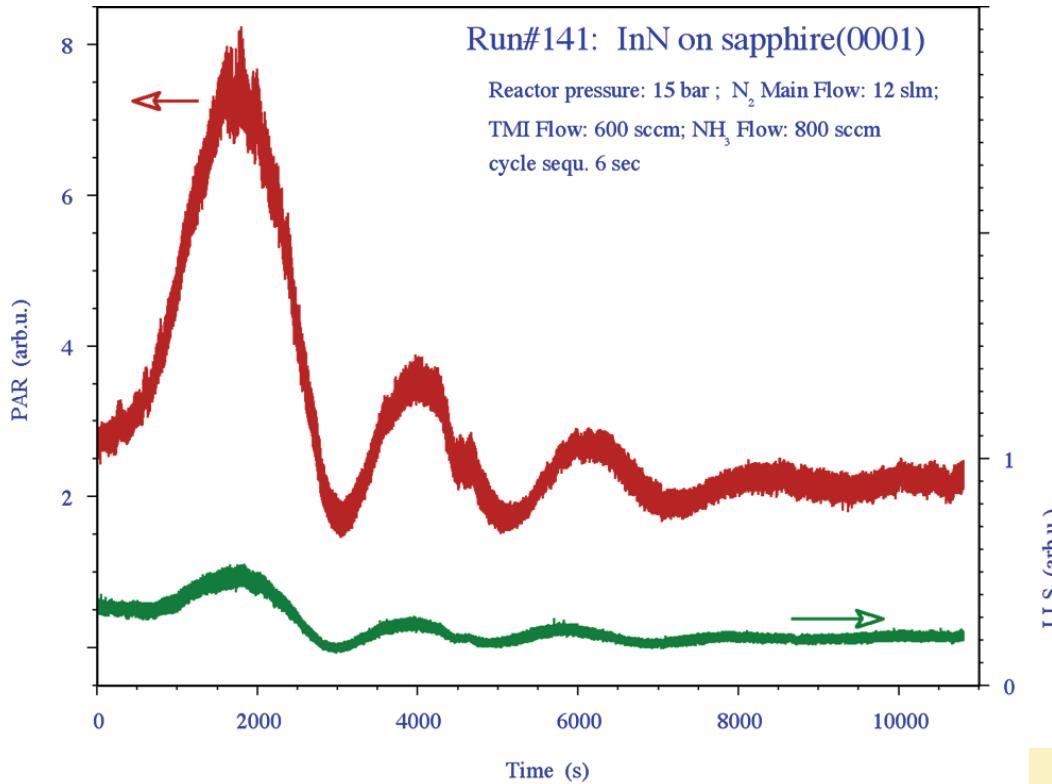
- Characterization of gas phase reactions: **UVAS**
- Surface chemistry & kinetics **PARS**
- Gas flow kinetics, Surface roughness **LLS**



\*In collaboration with Prof. K.J. Bachmann and T.H. Banks (NCSU)  
Supported by: NASA (real-time diagnostics); AFOSR (reactor development)

# Real-time growth monitoring at elevated pressures

N. Dietz  
Dept. Physics & Astronomy



## Principal Angle Reflectance Spectroscopy (PARS):

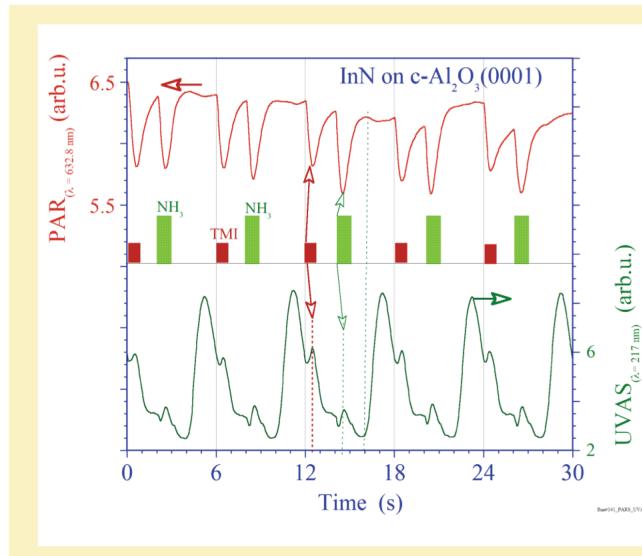
- Extract and track average growth rate and dielectric properties of growing layer
- Characterize and monitor surface chemistry processes with sub-monolayer resolution

## Laser Light Scattering (LLS):

- Monitor surface morphology / roughness
- Analyze reactor flow kinetics

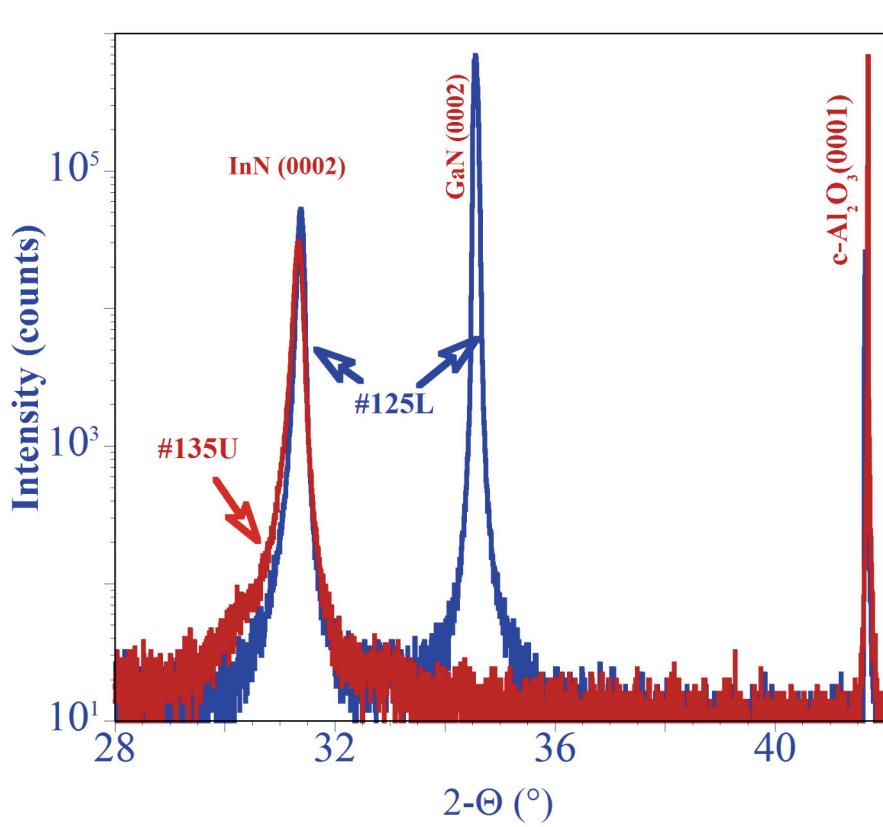
## Ultra-violet Absorption Spectroscopy (UVAS):

- Characterize precursor decomposition (e.g. NH<sub>3</sub> / TMI / TMG).
- Analyze/track precursor concentration/profile.



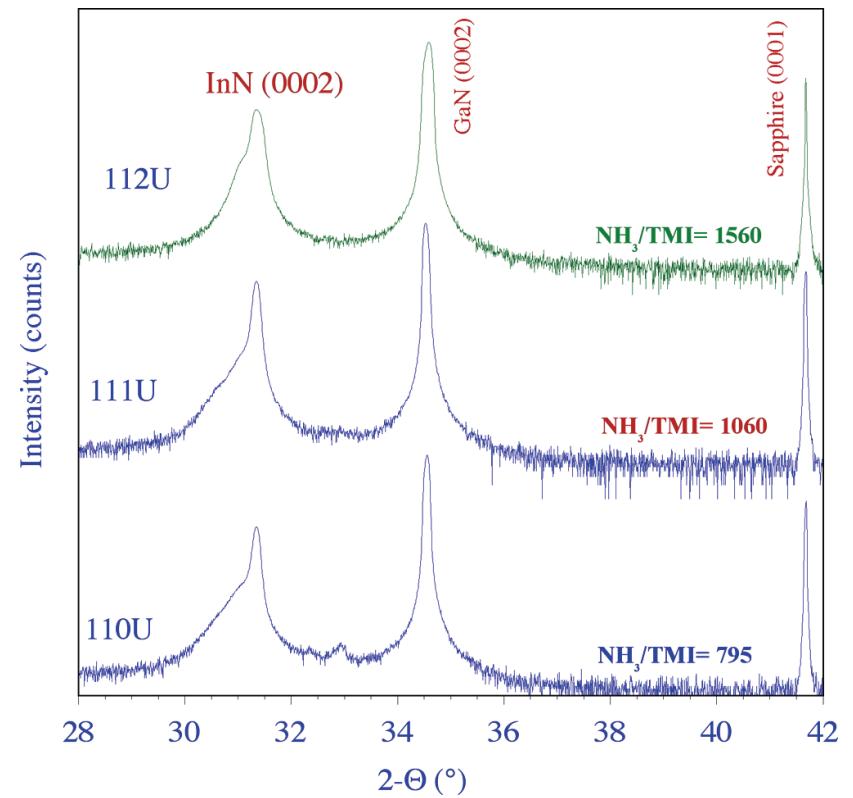
UVAS and PARS traces during steady-state growth conditions

# InN film characterization: XRD



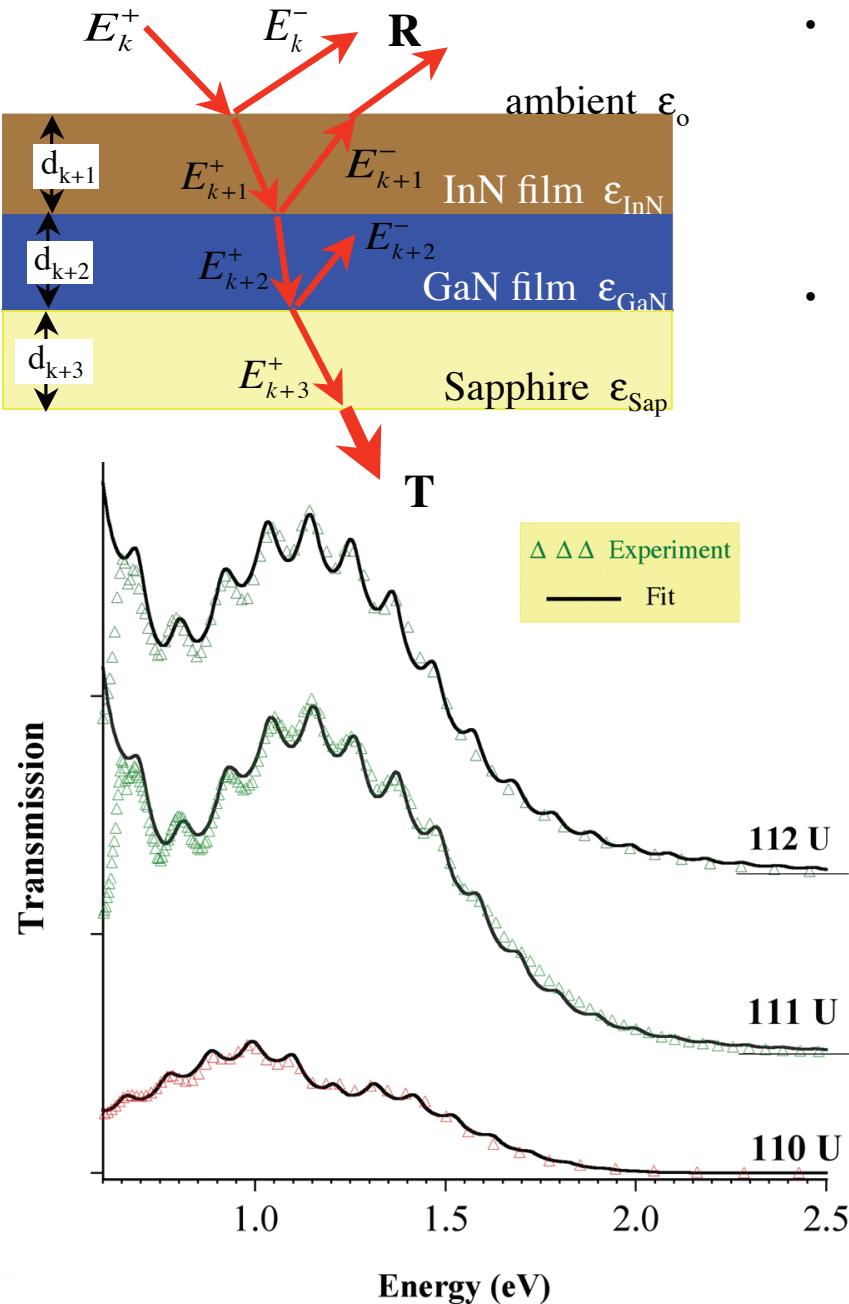
- Growth explored on sapphire and GaN/Sapphire
- For both templates, the growth of single phase InN (0002) epilayers achieved
- GaN/Sapphire FWHM  $\sim 385$  arcsec
- Sapphire FWHM  $\sim 492$  arc sec
- FWHM increases with lattice mismatch

## *Influence of Stoichiometry variations*



- All samples were grown on GaN (0002)/ Sapphire(0001) templates
- The hexagonal phase InN (0002) peaks are centered around  $2\Theta=31.3^{\circ}$
- FWHM values of InN(0002) increase with increasing  $\text{NH}_3/\text{TMI}$  ratio
- Lattice constants;  $c = 5.70 \text{ \AA}$ ,  $a = 3.57 \text{ \AA}$
- As the thickness of the InN film increases, InN (101) appear at  $\sim 33^{\circ}$  - indicating a shift in processing window!

# InN film characterization: Transmission

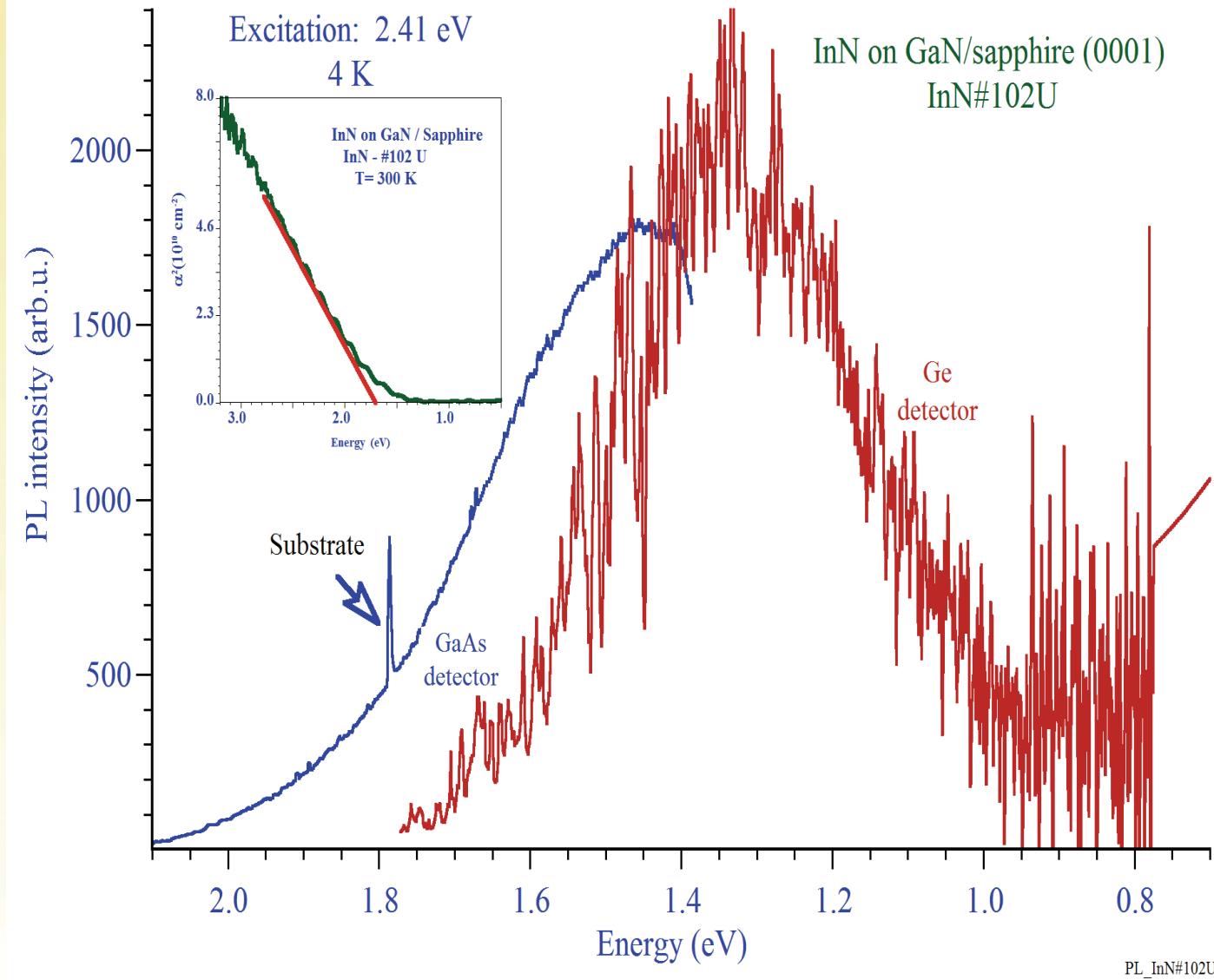


- Optical properties of InN ( $\epsilon_{InN}$ ,  $d_{InN}$ ) are determined by fitting the transmittance of an “ambient/InN/GaN/Sapphire” stack using the dielectric functions of the group III-nitrides based on a “model dielectric function” (MDF) approach<sup>1,2</sup>
- $$\epsilon_{InN}(\hbar\omega) = \epsilon_0(\hbar\omega) + \epsilon_{0x}(\hbar\omega) + \epsilon_1(\hbar\omega) + \epsilon_{1x}(\hbar\omega) + \epsilon_\infty$$
- A modified MDF model is used with two added oscillator at  $\approx 0.8$  and  $\approx 1.2$  eV, providing an excellent fit of the experimental transmission spectra:
- $$\epsilon_{InN}(\hbar\omega) = \epsilon_{InN}(\hbar\omega) + \sum_{n=1}^2 \frac{S_{ab}}{(E_{ab}^2 - E^2) - iE\Gamma_{ab}}$$
- $S_{ab}$ : lorentzian oscillator strength,  
 $E_{ab}$ : energetic position of absorption center,  
 $\Gamma_{ab}$ : damping constant
- The optical constants, the refractive index and the extinction coefficient are determined from the transmission measurements for the films with different molar ratios

Sample	#110 U	#111 U	#112 U
$d_{InN}$ (nm)	520	320	290
$\epsilon_\infty$	0.58	2.05	2.12
$E_0$ (eV)	1.92	1.58	1.48
$S_{ab1}$	0.46	0.37	0.37
$E_{ab1}$	0.64	0.8	0.8
$\Gamma_{ab1}$	0.57	0.34	0.35
$S_{ab2}$	0.075	0.01	-
$E_{ab2}$	1.2	1.3	-
$\Gamma_{ab2}$	0.22	0.1	-

1. A. B. Djusiric, and E. Herbert Li, *J. Appl. Phys.*, **85**, 2848(1999).
2. T. Kawashima, H. Yoshikawa, S. Adachi, S. Fukada, and K. Ohtsuka, *J. Appl. Phys.*, **82**, 3528(1997).

# InN film characterization: *Photoluminescence*



- PL spectra measured at 4 K
- broad PL features obtained due to the high defect concentration ( $> 10^{19} \text{ cm}^{-3}$ )
- The absorption coefficient (inset) was calculated by using the film thickness from the fitting of reflectance and transmission data
- The intercept of linear fits indicates absorption edge around 1.5 - 1.6 eV
- No PL detected below 1.0 eV

# The growth of InN by HPCVD

## *The need of high-pressure conditions*

- *Enabling the embedding of InN and indium-rich layers in wide-bandgap III-nitrides*
  - growth temperatures at 1100K - 1200K for pressures 10-15 bar
  - stabilization of volatile In-N-fragments under nitrogen blanket
- *improved layer quality*
  - higher mobility of growth surface fragments
  - InGaN alloys by suppressing decomposition (phase segregation)
- *engineered gas flow - and decomposition kinetics*
  - onset of ammonia decomposition lowered at higher pressures
  - MMIn and atomic In fragments dominant at pressures above 15 bar
  - low ammonia : TMI ratio needed

# InN growth by HPCVD - *Open tasks*

- What is the origin of absorption centers appearing around 1.2-1.0 eV and 0.8-0.7 eV ?
  - Are the energy levels associated with conduction band states? If so, why would they vary with In:N ratio?
  - Could it be that the oxygen defect energy states lay in the conduction band of InN and couples with InN band states?
- Next steps
  - Reduction of external impurities
  - Understanding the influence of oxygen impurity
  - Optimize InN layer properties and assess turbulent flow regime at ***higher reactor pressures (20-100bar)***
  - Move to indium rich  $\text{In}_{1-x}\text{Ga}_x\text{N}$  alloys & and embedded multiple  $\text{GaN}/\text{In}_{1-x}\text{Ga}_x\text{N}/\text{GaN}$  device structures.